

## Supplementary material: references

- [1] W. D. Sproul et al, "Control of reactive sputtering processes", *Thin Solid Films*, 491 (1), 1-17, 2005
- [2] K. Strijckmans et al, "Tutorial: Hysteresis during the reactive magnetron sputtering process", *J. Appl. Phys.*, 124 (24), 241101, 2018
- [3] Bever, J.V. et al, "A computational study of the double hysteresis phenomenon during reactive sputtering", *J. Phys. D: Appl. Phys.*, 55 (35), 355302, 2022
- [4] Bever, J.V. et al, "Influence of chemisorption on the double hysteresis phenomenon during reactive sputtering", *Appl. Surf. Sci.*, 613, 155901, 2023
- [5] R. Schelfhout et al, "The existence of a double S-shaped process curve during reactive magnetron sputtering", *Appl. Phys. Lett.*, 109 (11), 111605, 2016
- [6] D. Depla et al, "The role of the erosion groove during reactive sputter deposition", *Surf. Coat. Technol.*, 258, 1011-1015, 2014
- [7] P. Mareš, "Long-term stability and disappearing anode effects during reactive DC and pulsed bipolar magnetron sputtering of Al<sub>2</sub>O<sub>3</sub>", 173, 109161, 2020